



February 2006

FSUSB30

Low Power 2-Port Hi-Speed USB 2.0 (480Mbps) Switch

General Description

The FSUSB30 is a Low Power, 2-Port Hi-Speed USB 2.0 switch. This part is configured as a DPDT switch and is optimized for switching between two Hi-Speed (480Mbps) sources or a Hi-Speed and Full Speed (12Mbps) source. The FSUSB30 is compatible with the requirements of USB2.0 and features an extremely low On Capacitance (C_{ON}) of 6.5pF. The wide bandwidth of this device (720MHz), exceeds the bandwidth needed to pass the 3rd harmonic, resulting in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk also minimizes interference.

The FSUSB30 contains special circuitry on the D+/D- pins which allows the device to withstand an overvoltage condition. This device is also designed to minimize current consumption even when the control voltage applied to the S pin, is lower than the supply voltage (V_{CC}). This feature is especially valuable to Ultra-Portable applications such as cell phones, allowing for direct interface with the General Purpose I/Os of the baseband processor. Other applications include switching and connector sharing in portable cell phones, PDAs, digital cameras, printers, and notebook computers.

Features

- Low On Capacitance, 6.5pF (typical)
- Low On Resistance, 6.5Ω (typical)
- Low power consumption (1μA maximum)
 - 10μA maximum I_{CCT} over and expanded control voltage range ($V_{IN} = 2.6V$, $V_{CC} = 4.3V$)
- Wide -3dB bandwidth, >720MHz
- 8KV ESD protection
- Power OFF protection when $V_{CC} = 0V$, D+/D- pins can tolerate up to 4.3V
- Packaged in:
 - Pb-Free 10-lead MicroPak™ (1.6mm x 2.1mm)
 - Pb-Free 14-lead DQFN
 - Pb-Free 10-lead MSOP (preliminary)

Applications

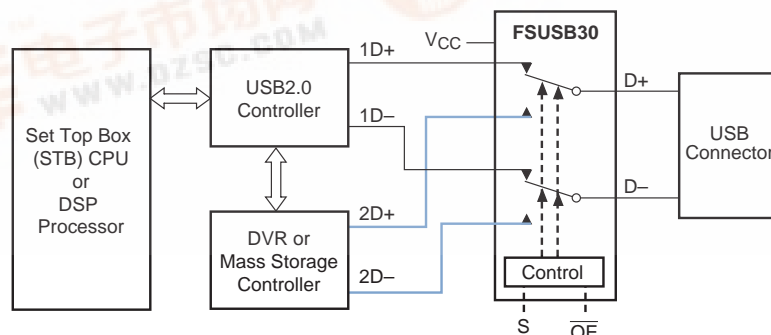
- Cell phone, PDA, Digital Camera, and Notebook
- LCD Monitor, TV, and Set-top Box

Ordering Information

Order Number	Package Number	Package Description
FSUSB30L10X	MAC010A	Pb-Free 10-Lead MicroPak, 1.6 mm x 2.1mm
FSUSB30BQX	MLP014A	Pb-Free 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm
FSUSB30MUX (Preliminary)	MUA10A	10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide

Pb-Free package per JEDEC J-STD-020B.

Application Diagram



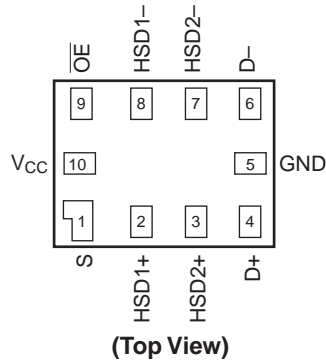
FSUSB30 Low Power 2-Port Hi-Speed USB 2.0 (480Mbps) Switch



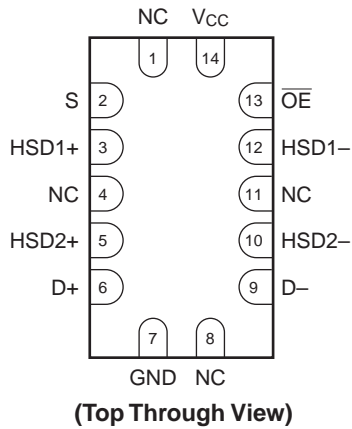
MicroPak™ is a trademark of Fairchild Semiconductor Corporation.

Connection Diagrams

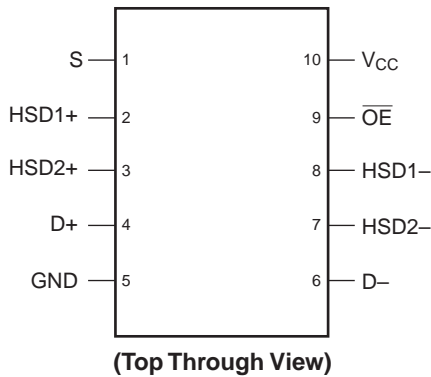
Pad Assignments for MicroPak



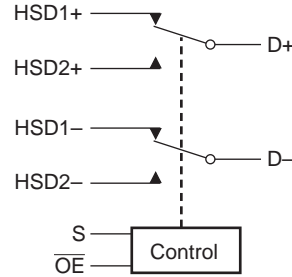
Pad Assignments for DQFN



Pin Assignment for MSOP



Analog Symbol



Pin Descriptions

Pin Name	Description
\overline{OE}	Bus Switch Enable
S	Select Input
D+, D-, HSDn+, HSDn-	Data Ports
NC	No Connect

Truth Table

S	\overline{OE}	Function
X	H	Disconnect
L	L	D+, D- = HSD1 _n
H	L	D+, D- = HSD2 _n

Absolute Maximum Ratings

(The “Absolute Maximum Ratings” are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The “Recommended Operating Conditions” table will define the conditions for actual device operation.)

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	-0.5V to +4.6V
V_{CNTRL}	DC Input Voltage ¹	-0.5V to +4.6V
V_{SW}	DC Switch Voltage ¹	
	HSDnX	-0.5V to $V_{CC} + 0.3V$
	D+, D-	-0.5V to +4.6V
	DC Input Diode Current	-50mA
	DC Output Current	50mA
	Storage Temperature	-65°C to +150°C
	ESD (Human Body Model)	
	All Pins	8 KV
	I/O to GND	8 KV

Recommended Operating Conditions²

Symbol	Parameter	Rating
V_{CC}	Supply Voltage	3.0V to 4.3V
V_{IN}	Control Input Voltage	0V to V_{CC}
	Switch Input Voltage	0V to V_{CC}
	Operating Temperature	-40°C to +85°C
	Thermal Resistance, 10 MicroPak	250°C/W

Notes:

1. The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed. DC switch voltage may never exceed 4.6V.
2. Control input must be held HIGH or LOW and it must not float.

DC Electrical Characteristics

(All typical values are @ 25°C unless otherwise specified.)

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C			Units
				Min	Typ	Max	
V _{IK}	Clamp Diode Voltage	I _{IN} = -18mA	3.0			-1.2	V
V _{IH}	Input Voltage HIGH		3.0 to 3.6	1.3			V
			4.3	1.7			V
V _{IL}	Input Voltage LOW		3.0 to 3.6			0.5	V
			4.3			0.7	V
I _{IN}	Control Input Leakage	V _{SW} = 0.0V to V _{CC}	4.3	-1.0		1.0	μA
I _{OZ}	OFF State Leakage	0 ≤ Dn, HSD1 _n , HSD2 _n ≤ V _{CC}	4.3	-2.0		2.0	μA
I _{OFF}	Power OFF Leakage Current (D+, D-)	V _{SW} = 0V to 4.3V, V _{CC} = 0V	0	-2.0		2.0	μA
R _{ON}	Switch On Resistance ³	V _{SW} = 0.8V, I _{ON} = -8mA	3.0		6.5	9.0	Ω
ΔR _{ON}	Delta R _{ON} ⁴	V _{SW} = 0.8V, I _{ON} = -8mA	3.0		0.35		Ω
R _{ON} Flatness	R _{ON} Flatness ³	V _{SW} = 0.0V – 1.0V, I _{ON} = -8mA	3.0		2.0		Ω
I _{CC}	Quiescent Supply Current	V _{CNTRL} = 0.0V or V _{CC} , I _{OUT} = 0	4.3			1.0	μA
I _{CC} T	Increase in I _{CC} Current per Control Voltage	V _{CNTRL} (control input) = 2.6V	4.3			10.0	μA

AC Electrical Characteristics

(All typical values are for V_{CC} = 3.3V @ 25°C unless otherwise specified.)

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C			Units	Figure Number
				Min	Typ	Max		
t _{ON}	Turn On Time S, \overline{OE} to Output	HD1 _n , HD2 _n = 0.8V, R _L = 50Ω, C _L = 5pF	3.0 to 3.6		13.0	30.0	ns	Figure 8
t _{OFF}	Turn OFF Time S, \overline{OE} to Output	HD1 _n , HD2 _n = 0.8V, R _L = 50Ω, C _L = 5pF	3.0 to 3.6		12.0	25.0	ns	Figure 8
t _{PD}	Propagation Delay ⁴	R _L = 50Ω, C _L = 5pF	3.3		0.25		ns	Figure 6 Figure 7
T _{BBM}	Break-Before-Make	R _L = 50Ω, C _L = 5pF, V _{IN} = 0.8V	3.0 to 3.6	2.0		6.5	ns	Figure 9
O _{IRR}	OFF Isolation (Non-Adjacent)	f = 240MHz, R _T = 50Ω	3.0 to 3.6		-30.0		dB	Figure 12
Xtalk	Non-Adjacent Channel Crosstalk	R _T = 50Ω, f = 240MHz	3.0 to 3.6		-45.0		dB	Figure 13
BW	-3dB Bandwidth	R _T = 50Ω, C _L = 0pF	3.0 to 3.6		720		MHz	Figure 11
		R _T = 50Ω, C _L = 5pF			550			

Notes:

3. Measured by the voltage drop between Dn, HSD1_n, HSD2_n pins at the indicated current through the switch. On Resistance is determined by the lower of the voltage on the two ports.
4. Guaranteed by characterization.

USB Hi-Speed Related AC Electrical Characteristics

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = -40°C to +85°C			Units	Figure Number
				Min	Typ	Max		
t _{SK(O)}	Channel-to-Channel Skew ⁵	R _L = 50Ω, C _L = 5pF	3.0 to 3.6		50.0		ps	Figure 6 Figure 10
t _{SK(P)}	Skew of Opposite Transitions of the Same Output ⁵	R _L = 50Ω, C _L = 5pF	3.0 to 3.6		20.0		ps	Figure 6 Figure 10
t _J	Total Jitter ⁵	R _L = 50Ω, C _L = 5pF, t _R = t _F = 500ps at 480 Mbps (PRBS = 2 ¹⁵ - 1)	3.0 to 3.6		200		ps	

Notes:

5. Guaranteed by characterization.

Capacitance

Symbol	Parameter	Conditions	T _A = -40°C to +85°C			Units	Figure Number
			Min	Typ	Max		
C _{IN}	Control Pin Input Capacitance	V _{CC} = 0V		1.5		pF	Figure 15
C _{ON}	D1 _n , D2 _n , Dn ON Capacitance	V _{CC} = 3.3, \overline{OE} = 0V		6.5		pF	Figure 14
C _{OFF}	D1 _n , D2 _n OFF Capacitance	V _{CC} and \overline{OE} = 3.3		2.5		pF	Figure 15

Typical Characteristics

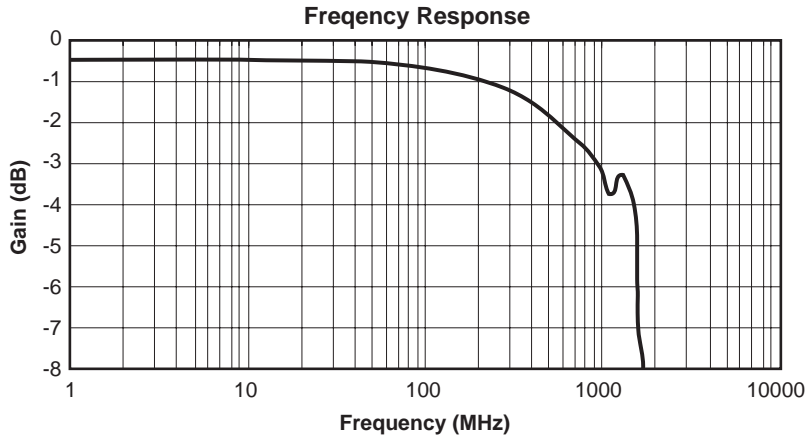


Figure 1. Gain vs. Frequency, $C_L = 0pF$, $V_{CC} = 3.3V$

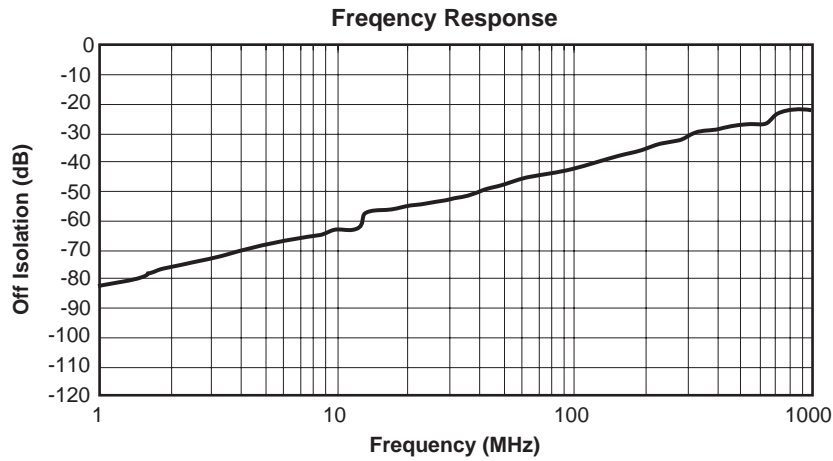


Figure 2. OFF Isolation, $V_{CC} = 3.3V$

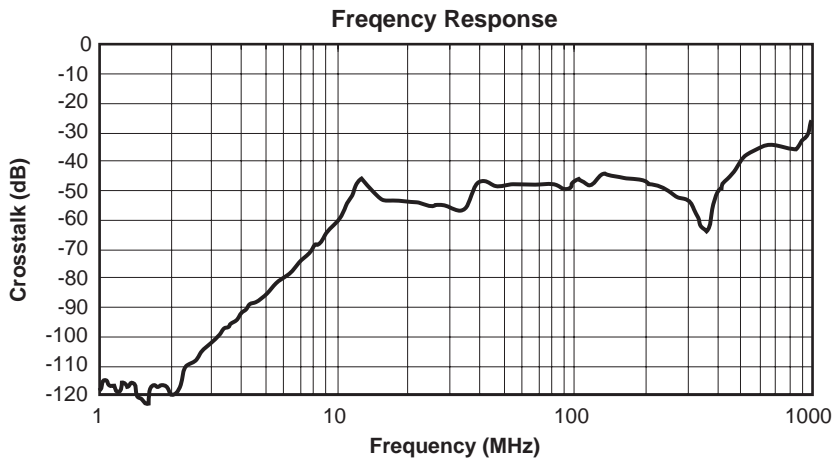


Figure 3. Crosstalk, $V_{CC} = 3.3V$

Test Diagrams

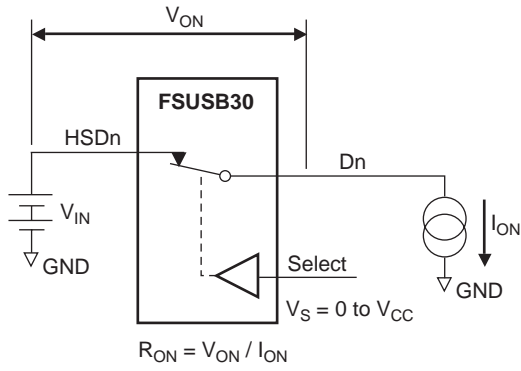
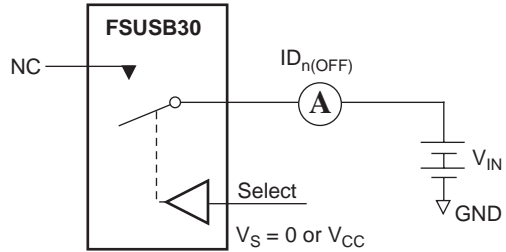
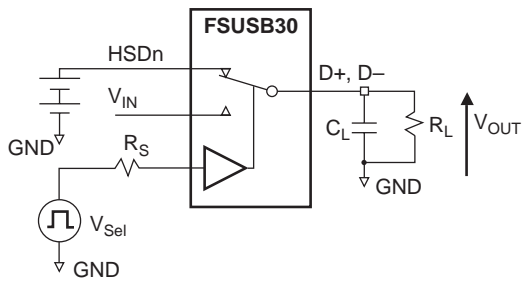


Figure 4. On Resistance



Each switch port is tested separately.

Figure 5. OFF Leakage



R_L , R_S , and C_L are functions of the application environment (see AC Electrical tables for specific values).

C_L includes test fixture and stray capacitance.

Figure 6. AC Test Circuit Load

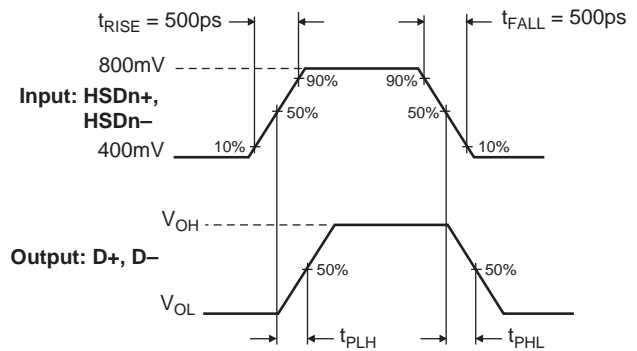


Figure 7. Switch Propagation Delay Waveforms

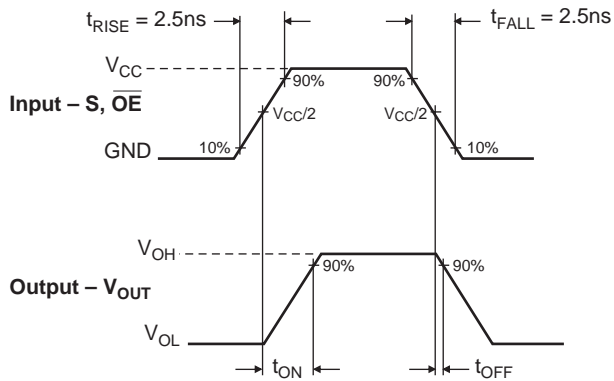


Figure 8. Turn ON / Turn OFF Waveform

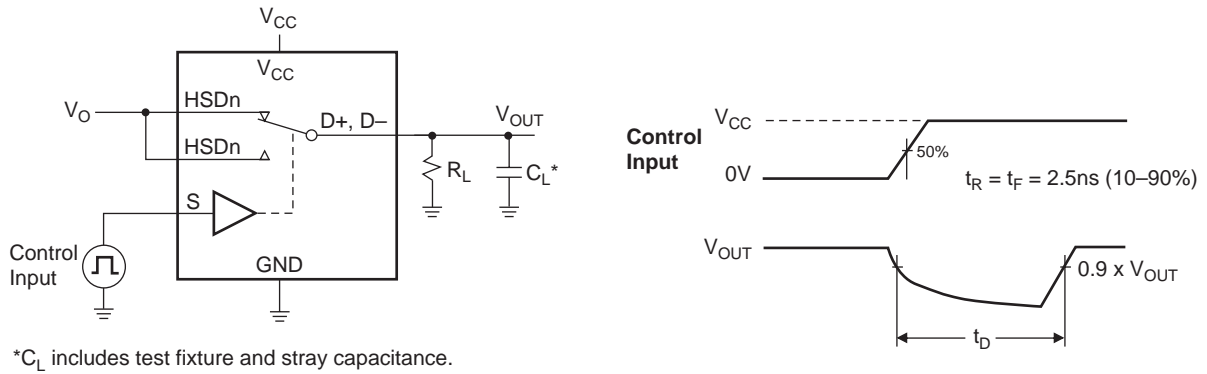


Figure 9. Break-before-Make (T_{BBM})

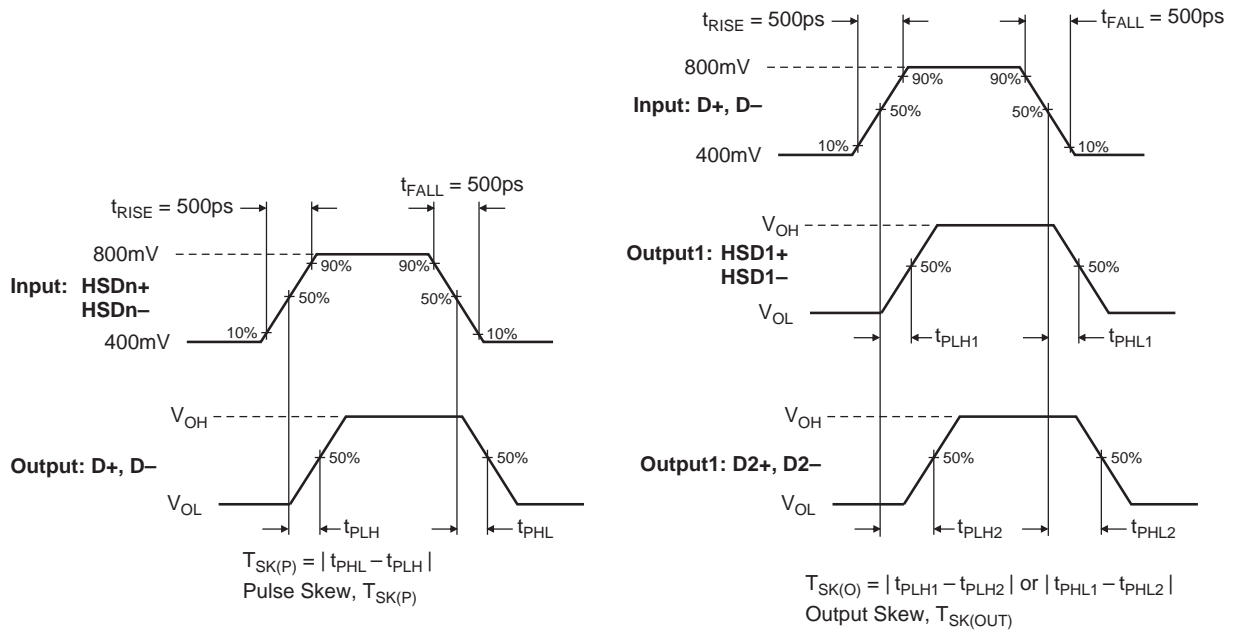


Figure 10. Switch Skew Tests

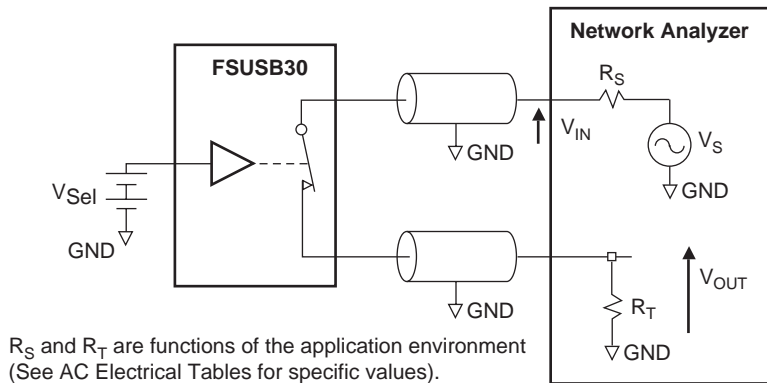


Figure 11. Bandwidth

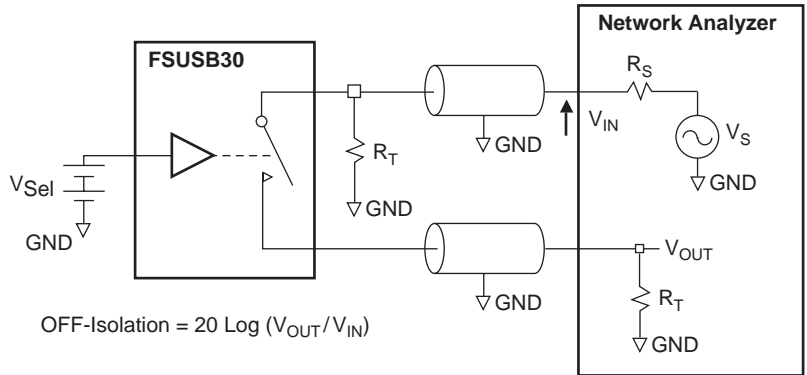


Figure 12. Channel OFF Isolation

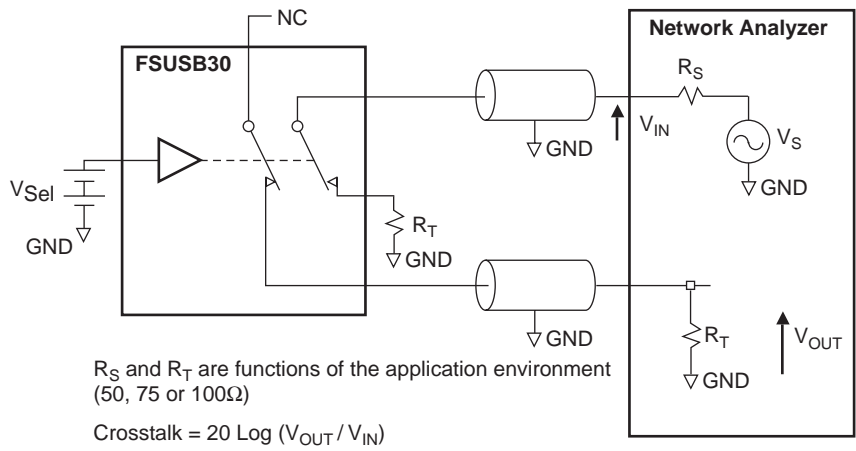


Figure 13. Non-Adjacent Channel-to-Channel Crosstalk

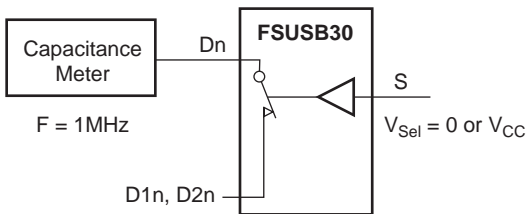


Figure 14. Channel ON Capacitance

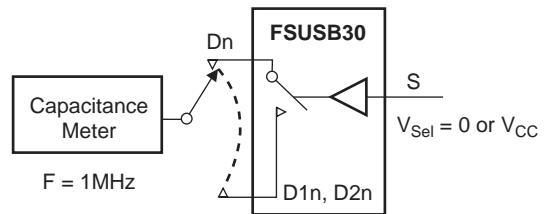


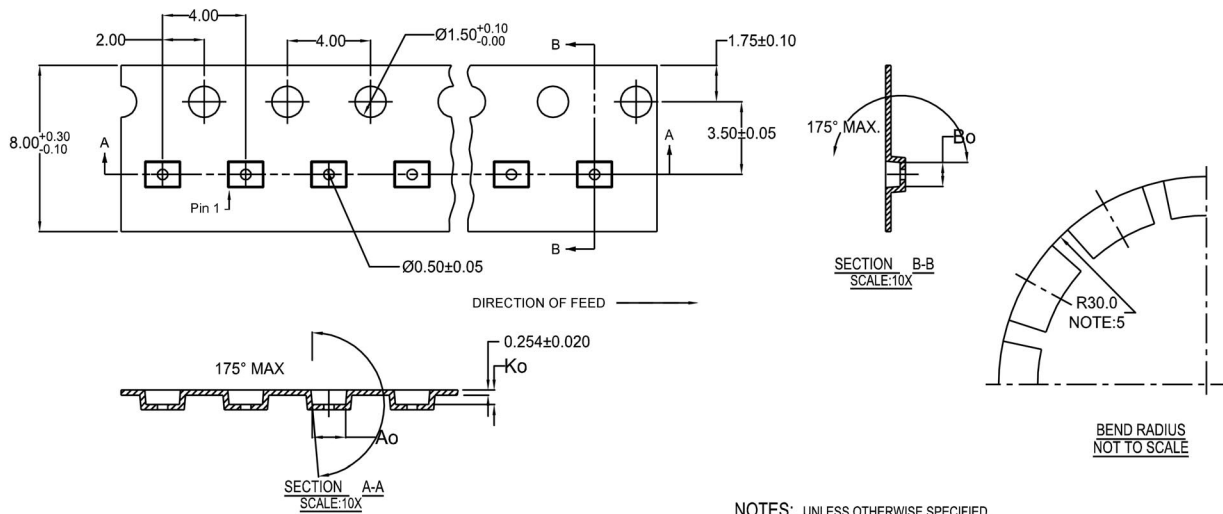
Figure 15. Channel OFF Capacitance

Tape and Reel Specifications

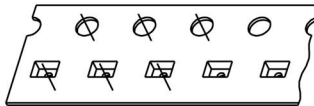
Tape Format for MircoPak

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
L10X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

Tape Dimension inches (millimeters)



10	300056	2.30 ± 0.05	1.78 ± 0.05	0.68 ± 0.05
8	300038	1.78 ± 0.05	1.78 ± 0.05	0.68 ± 0.05
6	300033	1.60 ± 0.05	1.15 ± 0.05	0.70 ± 0.05

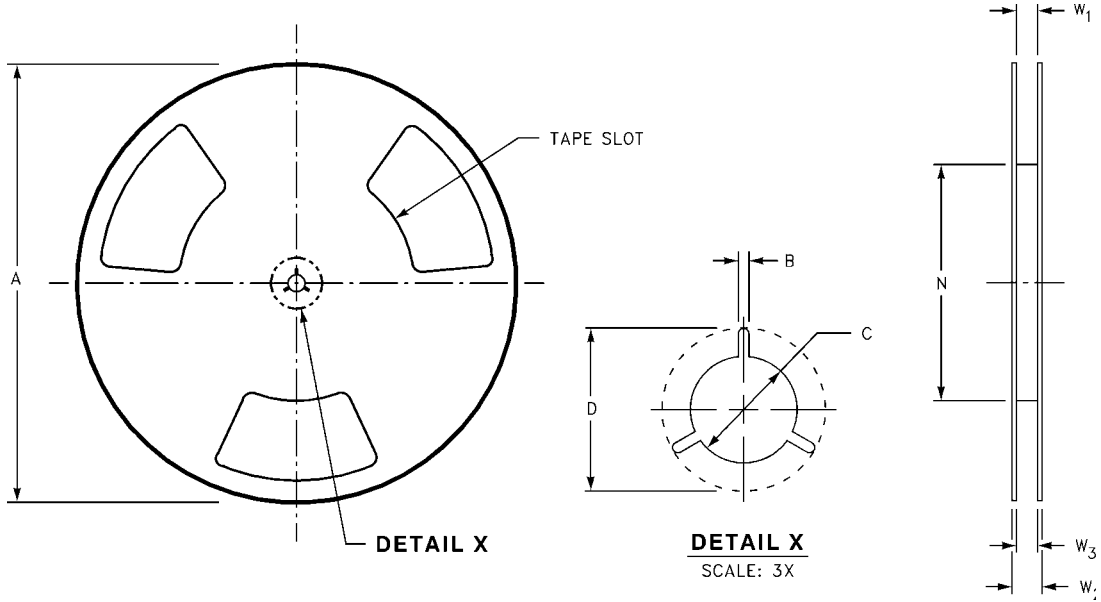


SCALE: 6X

NOTES: UNLESS OTHERWISE SPECIFIED

1. ACCUMULATED 50 SPROCKETS, SPROCKET HOLE PITCH IS 200.00 ± 0.30MM
2. NO INDICATED CORNER RADIUS IS 0.127MM
3. CAMBER NOT TO EXCEED 1MM IN 100MM
4. SMALLEST ALLOWABLE BENDING RADIUS
5. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE

Reel Dimension for MircoPak inches (millimeters)

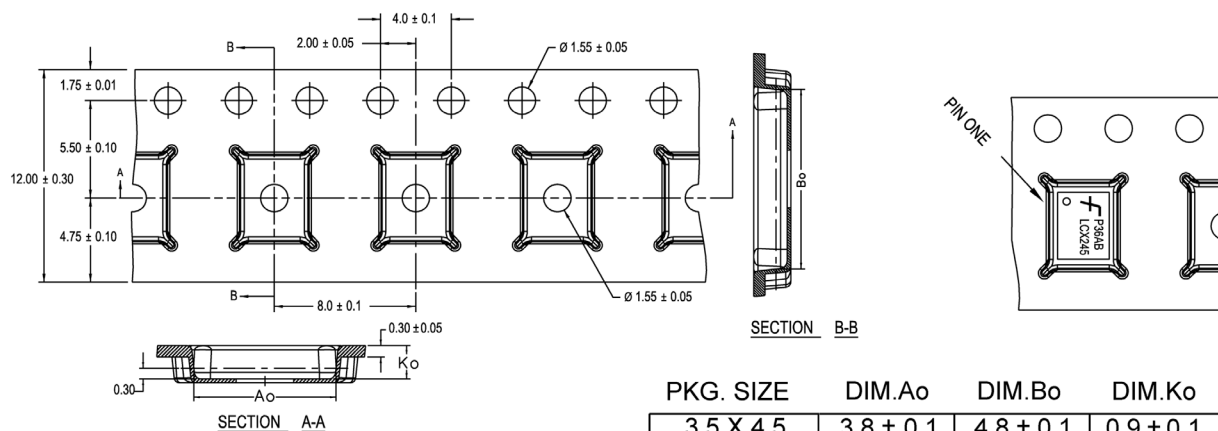


Tape Size	A	B	C	D	N	W1	W2	W3
8 mm	7.0 (177.8)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.331 + 0.059/-0.000 (8.40 + 1.50/-0.00)	0.567 (14.40)	W1 + 0.078/-0.039 (W1 + 2.00/-1.00)

Tape Format for DQFN

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
BQX	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	2500/3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

Tap Dimensions inches (millimeters)



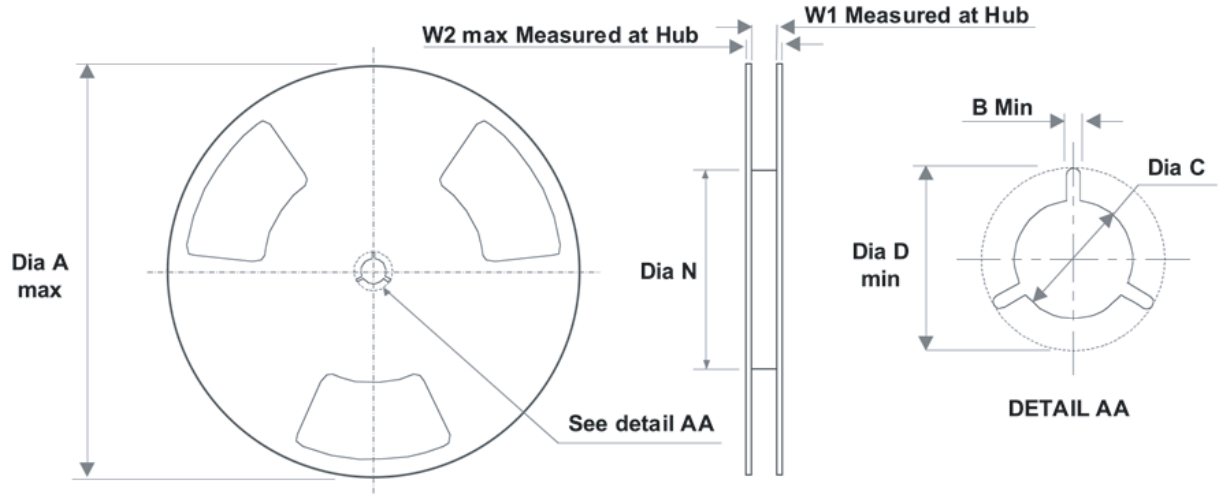
PKG. SIZE	DIM.Ao	DIM.Bo	DIM.Ko
3.5 X 4.5	3.8 ± 0.1	4.8 ± 0.1	0.9 ± 0.1
3.0 X 3.0	3.3 ± 0.1	3.3 ± 0.1	0.9 ± 0.1
2.5 X 4.5	2.8 ± 0.1	4.8 ± 0.1	0.9 ± 0.1
2.5 X 3.5	2.8 ± 0.1	3.8 ± 0.1	0.9 ± 0.1
2.5 X 3.0	2.8 ± 0.1	3.3 ± 0.1	0.9 ± 0.1
2.5 X 2.5	2.8 ± 0.1	2.8 ± 0.1	0.9 ± 0.1

DIMENSIONS ARE IN MILLIMETERS

NOTES: unless otherwise specified

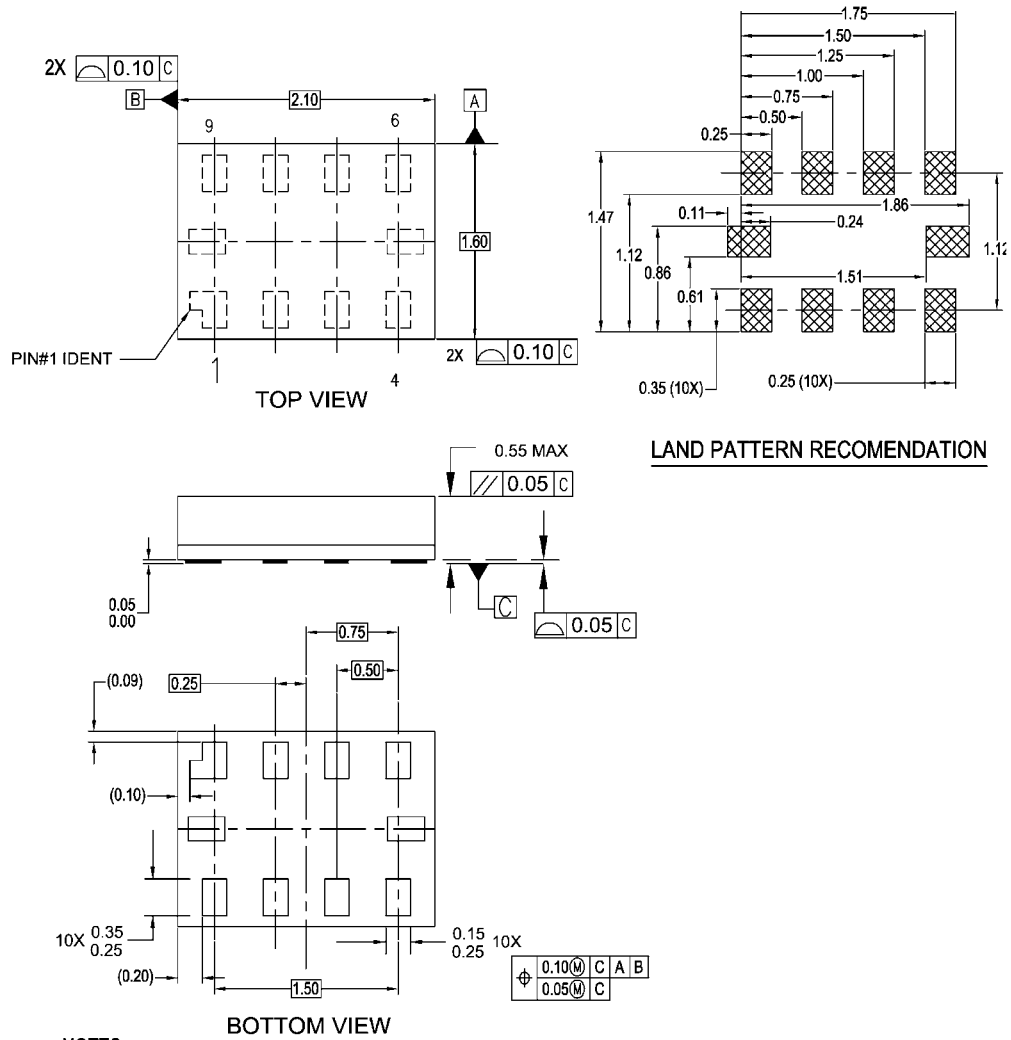
1. Cumulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
2. Smallest allowable bending radius.
3. Thru hole inside cavity is centered within cavity.
4. Tolerance is $\pm 0.002[0.05]$ for these dimensions on all 12mm tapes.
5. A_o and B_o measured on a plane 0.120[0.30] above the bottom of the pocket.
6. K_o measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
7. Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
8. Controlling dimension is millimeter. Dimension in inches rounded.

Reel Dimensions for DQFN inches (millimeters)



Tape Size	A	B	C	D	N	W1	W2
12 mm	13.0 (330)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	7.008 (178)	0.488 (12.4)	0.724 (18.4)

Physical Dimensions inches (millimeters) unless otherwise noted

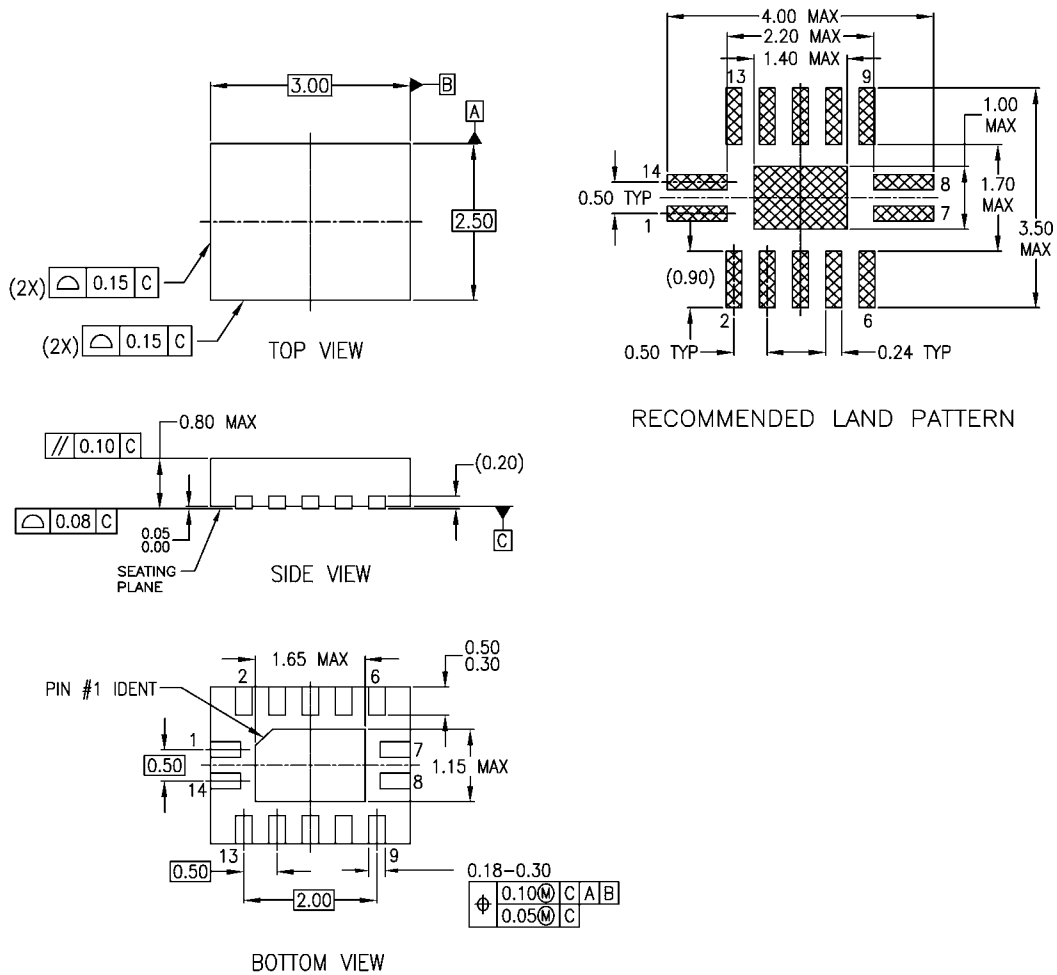


NOTES:

- A. PACKAGE CONFORMS TO JEDEC M0255, VARIATION UABD
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES CONFORMS TO ASME Y14.5M, 1994.

MAC010ARevC

**Pb-Free 10-Lead MicroPak, 1.6 mm x 2.1mm
Package Number MAC010A**

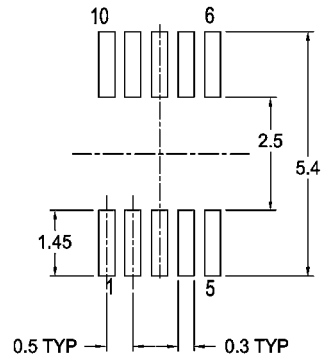
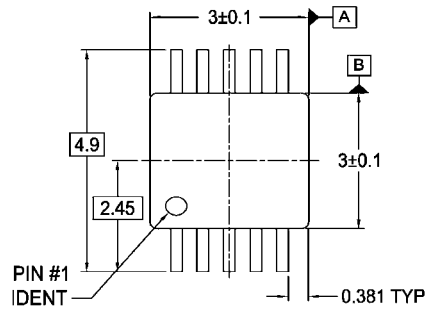


NOTES:

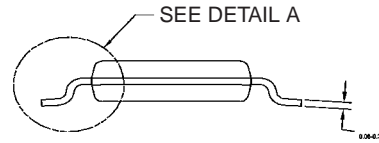
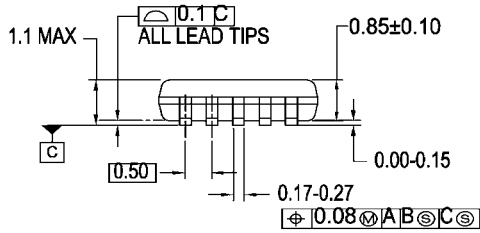
- A. CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AA
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP014ArevA

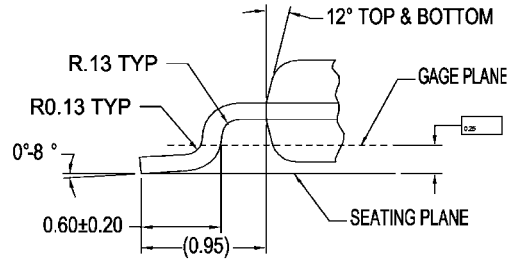
Pb-Free 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm Package Number MLP014A



LAND PATTERN RECOMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-187, VARIATION BA, REF NOTE 6, DATE 11/00.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.

MUA10AREVA

10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide
Package Number MUA10A

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CoolFET™	GlobalOptoisolator™	MicroPak™	QT Optoelectronics™	TinyLogic®
CROSSVOLT™	GTO™	MICROWIRE™	Quiet Series™	TINYOPTO™
DOME™	HiSeC™	MSX™	RapidConfigure™	TruTranslation™
EcoSPARK™	I ² C™	MSXPro™	RapidConnect™	UHC™
E ² C MOS™	i-Lo™	OCX™	µSerDes™	UltraFET®
EnSigna™	ImpliedDisconnect™	OCXPro™	ScalarPump™	UniFET™
FACT™	IntelliMAX™	OPTOLOGIC®	SILENT SWITCHER®	VCX™
FACT Quiet Series™		OPTOPLANAR™	SMART START™	Wire™
Across the board. Around the world.™		PACMAN™	SPM™	
The Power Franchise®		POP™	Stealth™	
Programmable Active Droop™		Power247™	SuperFET™	
		PowerEdge™	SuperSOT™-3	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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